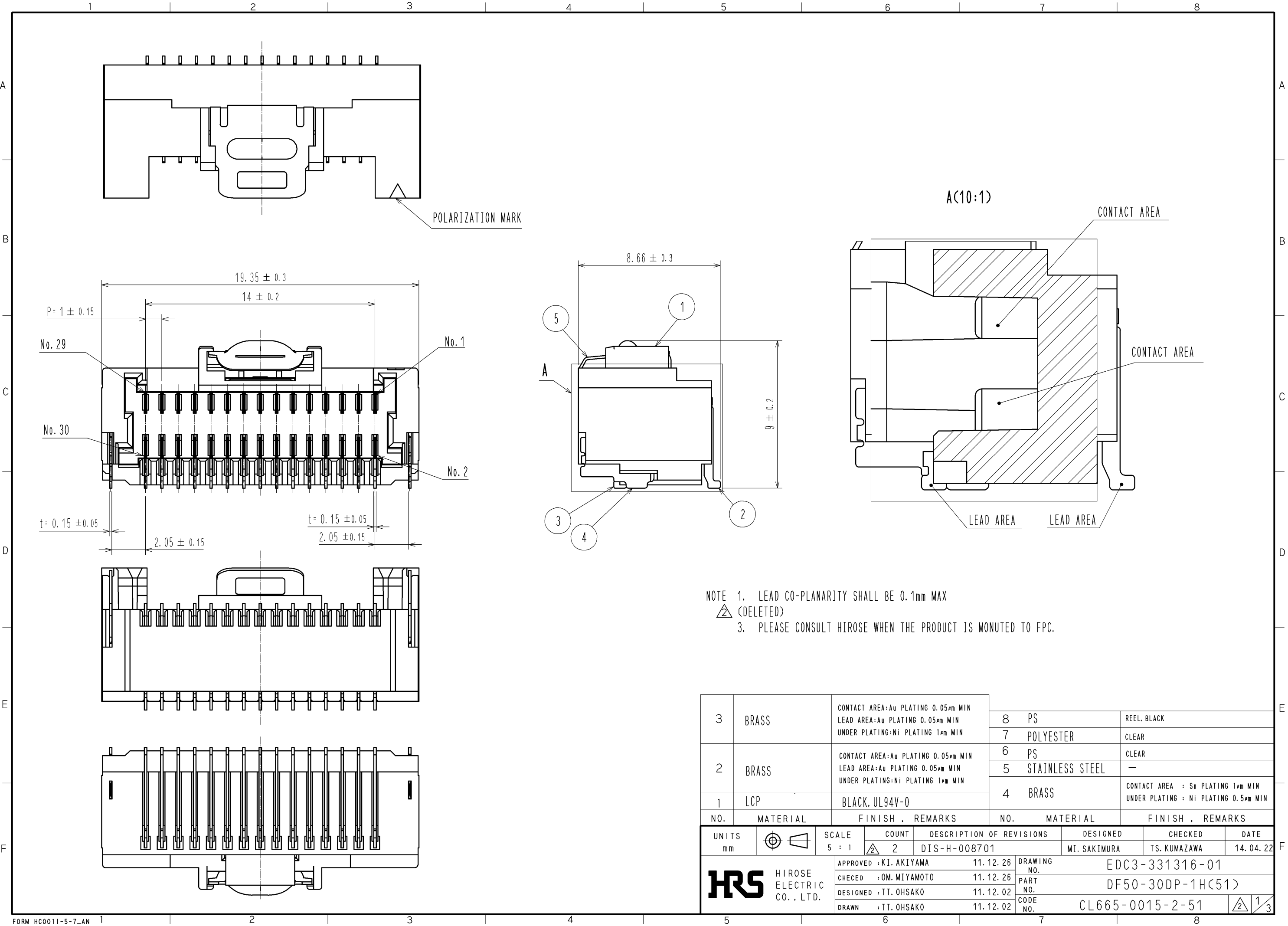
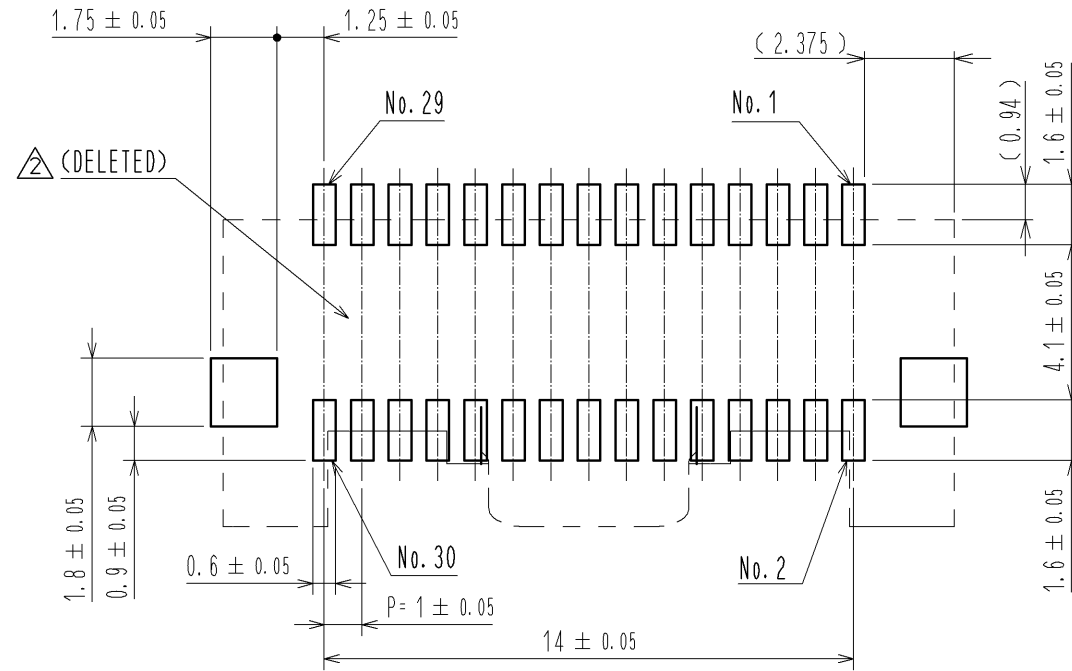




NOTE 1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX
(DELETED)
3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MONUTED TO FPC.

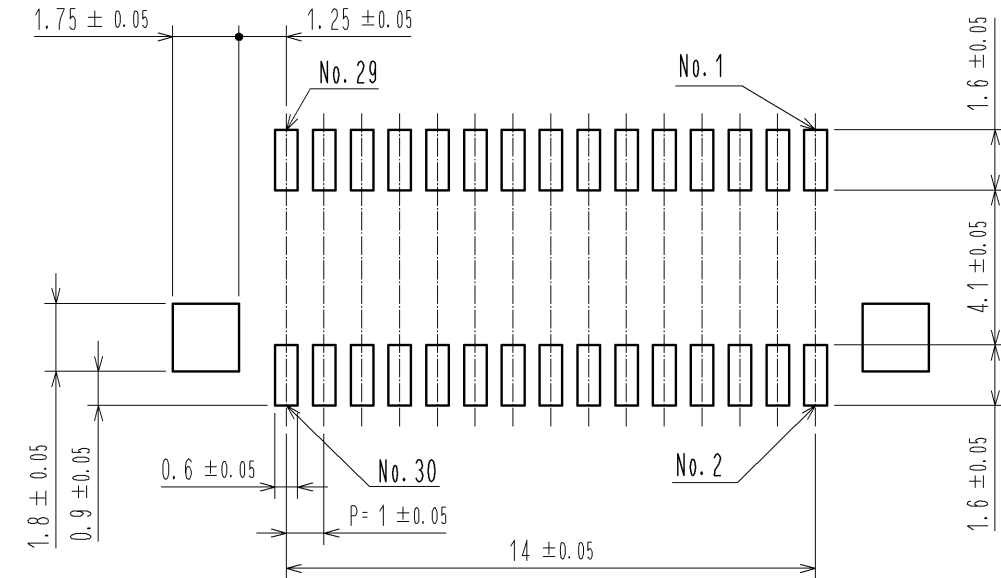
3	BRASS	CONTACT AREA: Au PLATING 0.05µm MIN LEAD AREA: Au PLATING 0.05µm MIN UNDER PLATING: Ni PLATING 1µm MIN	8	PS	REEL, BLACK
			7	POLYESTER	CLEAR
			6	PS	CLEAR
			5	STAINLESS STEEL	—
2	BRASS	CONTACT AREA: Au PLATING 0.05µm MIN LEAD AREA: Au PLATING 0.05µm MIN UNDER PLATING: Ni PLATING 1µm MIN	4	BRASS	CONTACT AREA : Sn PLATING 1µm MIN UNDER PLATING : Ni PLATING 0.5µm MIN
1	LCP	BLACK, UL94V-0			
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS mm			SCALE 5 : 1		
			COUNT 2		
			DESCRIPTION OF REVISIONS DIS-H-008701		
			DESIGNED MI. SAKIMURA		
			CHECKED TS. KUMAZAWA		
			DATE 14. 04. 22		
HRS HIROSE ELECTRIC CO., LTD.			APPROVED : KI. AKIYAMA 11. 12. 26		
			CHECED : OM. MIYAMOTO 11. 12. 26		
			DESIGNED : TT. OHSAKO 11. 12. 02		
			DRAWN : TT. OHSAKO 11. 12. 02		
			DRAWING NO. EDC3-331316-01		
			PART NO. DF50-30DP-1H(51)		
			CODE NO. CL665-0015-2-51		
			1/3		

RECOMMENDED PCB LAYOUT (MOUNTING SURFACE SIDE) (FREE)

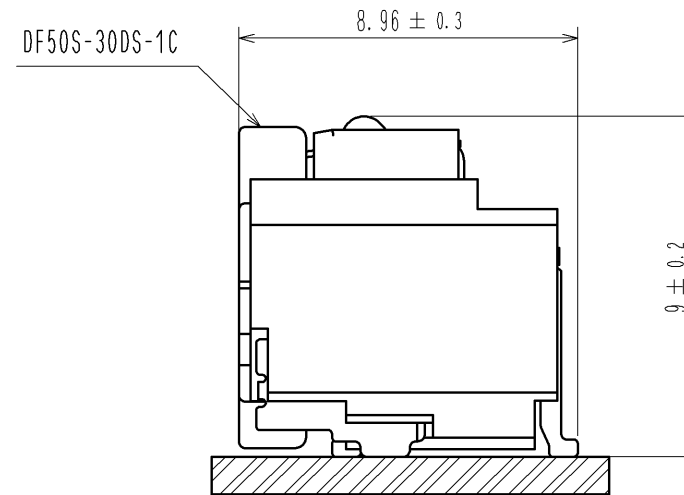
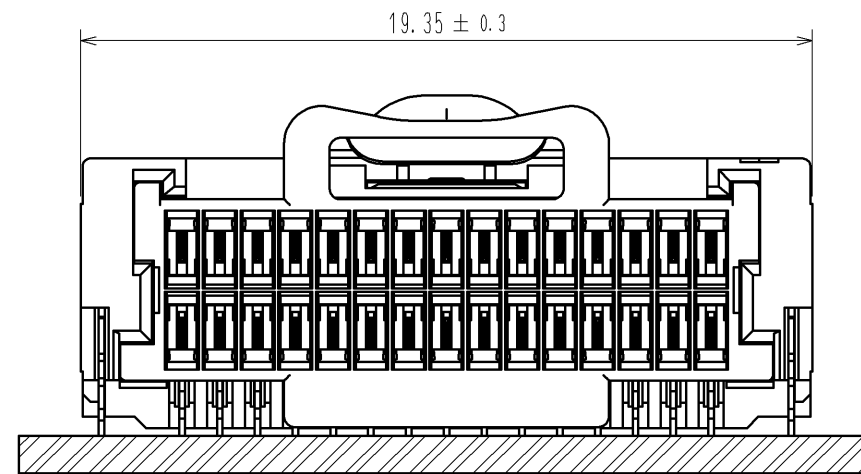


RECOMMENDED METAL MASK (FREE)

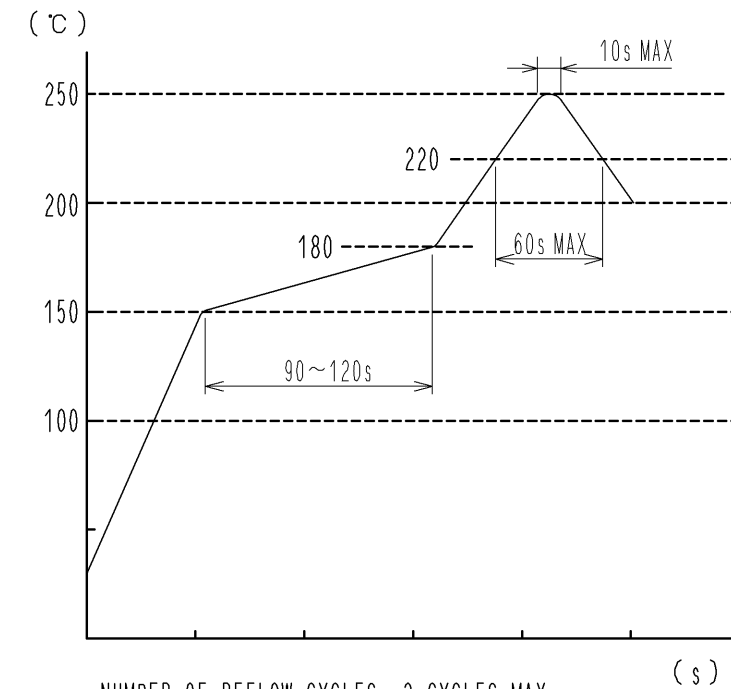
THICKNESS : 0.1mm
OPEN AREA RATIO:100%



MATING FIGURE (5 : 1)



REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
THE TEMPERATURE OF THIS PROFILE IS MEASURED ON THE LEAD TERMINAL.

WE RECOMMEND PERFORMING AN EVALUATION UNDER THE MOUNTING CONDITIONS YOU WILL BE USING BECAUSE IT COULD BE AFFECTED BY ANY CONDITION:TYPE OF SOLDER PASTE, SIZE OF PCB, MOUNTING MATERIAL etc..

HRS

DRAWING NO.	EDC3-331316-01
PART NO.	DF50-30DP-1H(51)
CODE NO.	CL665-0015-2-51

2/3

